

## CLAIM AMENDMENTS

1. (currently amended) An electret condenser microphone comprising:

a condenser section that comprises:

an electrically conductive diaphragm,

an electrically conductive back electrode board disposed in parallel opposition to said diaphragm with a gap space therebetween, and

an electret film formed on a surface of said back electrode board facing the diaphragm or on a surface of said diaphragm facing the back electrode board; and

a capsule accommodating said condenser section therein, said capsule having a side wall and a cover board affixed to a surface of said back electrode board facing away from the diaphragm so that said cover board and said back electrode board form a complex front board arrangement for the microphone; wherein

said back electrode board has a first through-aperture formed therethrough to communicate at ~~on~~ one end thereof to the gap space between the diaphragm and the back electrode board;

said cover board has a second through-aperture formed therethrough which communicates at one end thereof to an outside of said electret condenser microphone, and is positioned so as not to be in alignment with the first through-aperture with a distance therebetween which is longer than either thickness of the back electrode board and the cover board; and

said complex front board arrangement has a connecting path at an interface including opposing surfaces of said cover board and said back electrode board, wherein the connecting path extends perpendicularly to axes of said first and second through-apertures and is connected to the first and second through-apertures;

whereby said electret film communicates with the outside through said connecting path and said first and second through-apertures, and an ingress of grit from the outside to said electret film is suppressed by said connecting path.

2. (previously amended) The microphone as set forth in claim 1 wherein:

a surface of said cover board is affixed in intimate contact to a surface of said back electrode board, and

said connecting path of the complex front board arrangement is a connecting slit formed in at least one of the intimately affixed surfaces of the back electrode board and the cover board.

3. (original) The microphone as set forth in claim 2 wherein:

said connecting slit is formed as a V-shaped groove or channel in the surface of either one of the back electrode board and the cover board in which it is formed to a depth of up to 50  $\mu\text{m}$  so as to serve as an acoustic resistance slit.

4. (previously amended) The microphone as set forth in claim 2 wherein:

said capsule is in the form of an electrically conductive cylindrical cup having a front board serving as said cover board; and

said connecting slit of the complex board arrangement is formed in a surface of said front board facing the back electrode board.

5. (previously amended) The microphone as set forth in claim 2 wherein:

said capsule is in the form of an electrically conductive cylindrical cup having a front board serving as said cover board; and

said connecting slit of the complex board arrangement is formed in a surface of said back electrode board facing the front board.

6. (previously amended) The microphone as set forth in claim 4 wherein said electret film is disposed on the surface of said diaphragm facing the back electrode board.

7. (previously amended) The microphone as set forth in claim 5 wherein said electret film is disposed on the surface of said diaphragm facing the back electrode board.

8. (previously amended) The microphone as set forth in claim 1 wherein:

said complex front board arrangement further comprises an annular disk-shaped spacer;

said cover board is affixed to said back electrode board with said annular disk-shaped spacer interposed therebetween;

a gap space is formed at said interface between said back electrode board and said cover board and

said gap space is adapted to act as said connecting path of the complex front board arrangement.

9. (previously amended) The microphone as set forth in claim 8 wherein:

said capsule is in the form of an electrically conductive cylindrical cup having a front board serving as said cover board; and

said electret film is disposed on the surface of said back electrode board facing said diaphragm.

10. (previously amended) The microphone as set forth in claim 8 wherein:

said capsule is in the form of an electrically conductive cylindrical cup having a front board serving as said cover board; and

said electret film is disposed on the surface of said diaphragm facing the back electrode board.

11. (previously added) The microphone as set forth in claim 4 wherein said electret film is disposed on the surface of said back electrode board facing the diaphragm.

12. (previously added) The microphone as set forth in claim 5 wherein said electret film is disposed on the surface of said back electrode board facing the diaphragm.